Please read this notice before using the TAIYO YUDEN products.

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## Product Information in this Catalog

Product information in this catalog is as of March 2023. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

# Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

### Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

### Limited Application

### 1. Equipment Intended for Use

The products listed in this catalog are intended for general-purpose and standard use in general electronic equipment for consumer (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets, or the equipment approved separately by TAIYO YUDEN.

TAIYO YUDEN has the product series intended for use in the following equipment. Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

Application	Product Series	Quality Grade⁺³	
Application	Equipment <sup>+1</sup>	Category (Part Number Code *2)	
Automotive	Automotive Electronic Equipment (POWERTRAIN, SAFETY)	А	1
Automotive	Automotive Electronic Equipment (BODY & CHASSIS, INFOTAINMENT)	С	2
Industrial	Telecommunications Infrastructure and Industrial Equipment	В	2
Medical	Medical Devices classified as GHTF Class C (Japan Class III)	Μ	2
Medical	Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)	L	3
Consumer	General Electronic Equipment	S	3
	Only for Mobile Devices *4	E	4

\*Notes:1. Based on the general specifications required for electronic components for such equipment, which are recognized by TAIYO YUDEN, the use of each product series for the equipment is recommended. Please be sure to contact TAIYO YUDEN before using our products for equipment other than those covered by the product series.

2. On each of our part number, the 2nd code from the left is a code indicating the "Category" as shown in the above table. For details, please check the explanatory materials regarding the part numbering system of each of our products.

3. Each product series is assigned a "Quality Grade" from 1 to 4 in order of higher quality. Please do not incorporate a product into any equipment with a higher Quality Grade than the Quality Grade of such product without the prior written consent of TAIYO YUDEN.

4. The applications covered by this product series are limited to mobile devices (smartphone, tablet PC, smartwatch, handheld game console, etc.) among general electronic equipment for consumer. The design, specifications and operating environment, etc. differ from those of the product series for "General Electronic Equipment" (Category: S), so please check the individual product specification sheets for details. The product series for "General Electronic Equipment" (Category: S) can also be used for mobile devices.

# 2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

(1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)

(2) Traffic signal equipment

(3) Disaster prevention equipment, crime prevention equipment

- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, data-processing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

### 3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability. (1) Aerospace equipment (artificial satellite, rocket, etc.)

- (2) Aviation equipment \*1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices \*2
- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)

(5) Undersea equipment (submarine repeating equipment, etc.)

(6) Military equipment

(7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

- \*Notes:1. There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
  - 2. Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

### 4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

### Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

### Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

### Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves conforming to the product specifications specified in the individual product specification sheets, and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement, provided, however, that our products shall be used for general-purpose and standard use in the equipment specified in this catalog or the individual product specification sheets.

# TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

# Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

# Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LSAN series for General Electronic Equipment for Consumer

				Code in front of Ser	ies have bee	n extracted from	n Part num	ber, which describes the segment of products, such as kinds and	characteris
									REFLO
PART	NUMB	ER				* Operat	ng Tem	p.:-40~+105°C(Including self-generated heat)	
	^		6						
LS	<u>А</u> 1)	N B 2 0 1 2 3	6	<u>ккт</u> (4) (5)	R 6	0 <u>  M  </u> ⑦	(	8	
(	IJ	(2) $(3)$		4 5	୭	$\mathcal{O}$	Q		
①Series									
Coo									
(1)(2)(							0		
LSA	AN	Wire-wound Metal Pow	er Induc	tor for General Ele	ctronic E	quipment for	Consu	mer	_
(1) Produ	ct Gro	pup				(3) Type			
Code						Code			
L		Inductor	S			Α		Metal Wire-wound	_
(2) Categ	onu					(4) Featu	res Ch	aracteristics	
Code	Ory	Recommended equipment		Quality Grade		Code	103, 011		_
s	(	General Electronic Equipme	nt	3		N		Standard Power choke	_
3		for Consumer		3					
2 Featur	es					⑤Packag	ving		
Coo		Fea	ture			Co		Packaging	
В		L-shape electrode	Ag-resi	n × Sn-plate)		Т		Taping	_
വം									
3Dimens	sions (			Dimensions		6 Nomina			-
Coo	de	Type(inch)		$L \times W$ [mm]		(exam		Nominal inductance[µH]	
201	6	2016(0806)		2.0 × 1.6		R4	7	0.47	
252	20	2520(1008)		2.5 × 2.0		1R		1.0	_
<u>م</u>		<b>T</b> )				4R		4.7	
4Dimens Coo		Dimensior	s(T)[m	ml		₩R=De	cimal po	bint	
Kł			.0			⑦Inducta	ance tol	erance	
M			.2			Co		Inductance tolerance	
						Ν		±20%	
						<b>O</b> I			
						(8)Interna	ii coae		
STANE	DARD	EXTERNAL DIMENSIONS	STAN	DARD QUANTITY					
				Re	commend	ed Land Pat	terns		

### **Recommended Land Patterns**

Surface Mounting

•Mounting and soldering conditions should be checked beforehand.

• Applicable soldering process to these products is reflow soldering only.

licable soldering process to these products is reflow soldering only.									
	Туре	А	В	С					
c	2016	0.7	0.8	1.8					
	2520	0.8	1.2	2.0					
				Unit : mm					

Туре	L	W	т	e	Standard quantity[pcs] Taping
2016KK	2.0±0.1	$1.6 \pm 0.1$	1.0 max	$0.5 \pm 0.3$	3000
2010KK	$(0.079 \pm 0.004)$	$(0.063 \pm 0.004)$	(0.039 max)	$(0.020 \pm 0.012)$	3000
2520KK	$2.5 \pm 0.2$	$2.0 \pm 0.2$	1.0 max	$0.5 \pm 0.3$	3000
ZJZUKK	(0.098±0.008)		(0.039 max)	$(0.020 \pm 0.012)$	3000
2520MK	2.5±0.2	$2.0 \pm 0.2$	1.2 max	$0.5 \pm 0.3$	3000
2520MK	$(0.098 \pm 0.008)$	$(0.079 \pm 0.008)$	(0.047 max)	$(0.020 \pm 0.012)$	3000
					Linit mm (inch)

Unit:mm(inch)



PART NUMBER

<b>0</b> 2016KK type		【Thickn	ess:1.0mm max.】						
	Old and another		New Seal Sedenation		Self-resonant frequency [MHz] (min.)	DC Resistance [Ω](max.)	Rated current ※) [mA](max.)		Managera
New part number	Old part number (for reference)	EHS	Nominal inductance [ µ H]	Inductance tolerance			Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]
LSANB2016KKTR24M	MAKK2016TR24M	RoHS	0.24	±20%	-	0.037	4,200	3,000	2
LSANB2016KKTR33M	MAKK2016TR33M	RoHS	0.33	±20%	-	0.040	3,600	3,200	2
LSANB2016KKTR47M	MAKK2016TR47M	RoHS	0.47	±20%	-	0.460	3,200	2,800	2
LSANB2016KKTR68M	MAKK2016TR68M	RoHS	0.68	±20%	-	0.065	2,500	2,500	2
LSANB2016KKT1R0M	MAKK2016T1R0M	RoHS	1.0	±20%	-	0.075	2,200	2,200	2
LSANB2016KKT1R5M	MAKK2016T1R5M	RoHS	1.5	±20%	-	0.130	1,600	1,650	2
LSANB2016KKT2R2M	MAKK2016T2R2M	RoHS	2.2	±20%	-	0.160	1,500	1,500	2
LSANB2016KKT3R3M	MAKK2016T3R3M	RoHS	3.3	±20%	-	0.255	1,150	1,200	2
LSANB2016KKT4R7M	MAKK2016T4R7M	RoHS	4.7	±20%	-	0.380	1,000	950	2

<b>2</b> 520KK	type

### [Thickness: 1.0mm max.]

	Old and any how		Manada al faste stances		Self-resonant	DO Desistence	Rated current 💥) [mA](max.)		Manager	
New part number	Old part number (for reference)	EHS	Nominal inductance [ µ H]	Inductance tolerance	frequency [MHz](min.)	DC Resistance [Ω](max.)	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	
LSANB2520KKTR33M	MAKK2520TR33M	RoHS	0.33	±20%	-	0.038	4,700	3,500	2	
LSANB2520KKTR47M	MAKK2520TR47M	RoHS	0.47	±20%	-	0.046	3,900	3,200	2	
LSANB2520KKTR68M	MAKK2520TR68M	RoHS	0.68	±20%	-	0.059	3,700	2,900	2	
LSANB2520KKT1R0M	MAKK2520T1R0M	RoHS	1.0	±20%	-	0.072	2,700	2,500	2	
LSANB2520KKT1R5M	MAKK2520T1R5M	RoHS	1.5	±20%	-	0.125	2,300	1,800	2	
LSANB2520KKT2R2M	MAKK2520T2R2M	RoHS	2.2	±20%	-	0.156	1,900	1,500	2	
LSANB2520KKT3R3M	MAKK2520T3R3M	RoHS	3.3	±20%	-	0.200	1,550	1,300	2	
LSANB2520KKT4R7M	MAKK2520T4R7M	RoHS	4.7	±20%	-	0.300	1,300	1,100	2	

2520MK type [Thickness: 1.2mm max.]

			N		Self-resonant		Rated current	Measuring	
New part number	w part number Old part number (for reference) EHS [ µ H] Indu		Inductance tolerance frequency [MHz] (min		DC Resistance [Ω](max.)	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]	
LSANB2520MKTR47M	MAMK2520TR47M	RoHS	0.47	±20%	-	0.039	4,200	3,400	2
LSANB2520MKTR68M	MAMK2520TR68M	RoHS	0.68	±20%	-	0.048	3,200	3,200	2
LSANB2520MKT1R0M	MAMK2520T1R0M	RoHS	1.0	±20%	-	0.059	3,100	2,700	2
LSANB2520MKT2R2M	MAMK2520T2R2M	RoHS	2.2	±20%	-	0.110	2,000	1,900	2
LSANB2520MKT3R3M	MAMK2520T3R3M	RoHS	3.3	±20%	-	0.156	1,800	1,700	2
LSANB2520MKT4R7M	MAMK2520T4R7M	RoHS	4.7	±20%	-	0.260	1,500	1,300	2

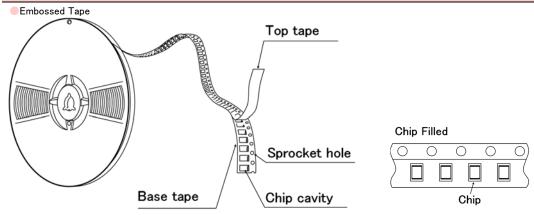
%) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)



# PACKAGING

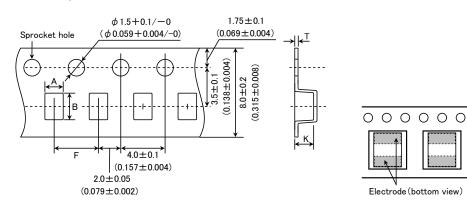
①Minimum Quantity						
Turna	Standard Quantity [pcs]					
Туре	Tape & Reel					
2016KK	3000					
2520KK	3000					
2520MK	3000					

# (2) Tape Material



### ③Taping dimensions

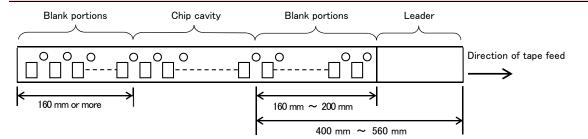
Embossed tape 8mm wide (0.315 inches wide)



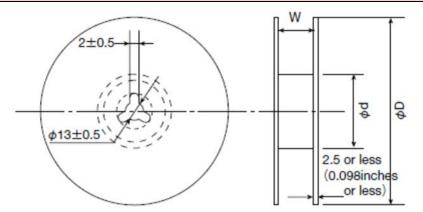
Туре	Chip	cavity	Insertion pitch	Insertion pitch Tape th		
туре	A	В	F	Т	K	
2016KK	1.9±0.1	2.3±0.1	4.0±0.1	$0.25 \pm 0.05$	1.2 max	
2010KK	$(0.075 \pm 0.004)$	$(0.091 \pm 0.004)$	$(0.157 \pm 0.004)$	$(0.009 \pm 0.002)$	(0.047 max)	
2520KK	2.3±0.1	2.8±0.1	4.0±0.1	$0.3 \pm 0.05$	1.25 max	
	$(0.091 \pm 0.004)$	$(0.110 \pm 0.004)$	$(0.157 \pm 0.004)$	$(0.012 \pm 0.002)$	(0.049 max)	
050014/	2.3±0.1	2.8±0.1	4.0±0.1	$0.3 \pm 0.05$	1.4 max	
2520MK	$(0.091 \pm 0.004)$	$(0.110 \pm 0.004)$	(0.157±0.004)	$(0.012 \pm 0.002)$	(0.055 max)	
				()		

Unit:mm(inch)

# ④Leader and Blank portion



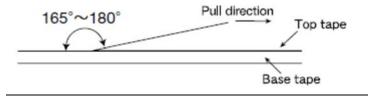
# ⑤Reel size



Туре	F	Reel size (Reference values)						
туре	φD	фd	W					
2016KK	180+0/-3	60+1/ 0	$10.0 \pm 1.5$					
2520KK	(7.087+0/-0.118)	60+1/-0 (2.36+0.039/0)	$(0.394 \pm 0.059)$					
2520MK	(7.067+0/-0.118)	(2.30+0.039/0)	$(0.334 \pm 0.009)$					
			Unit:mm(inch)					

# 6 Top Tape Strength

The top The top tape requires a peel-off force of 0.1 to 1.2N in the direction of the arrow as illustrated below.





Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LSAN series for General Electronic Equipment for Consumer Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LSAP series for General Electronic Equipment for Consumer Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LLAN series

for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

Wire-wound Metal Power Inductors MCOIL<sup>™</sup> LLAP series

for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

# RELIABILITY DATA

1. Operating Temperature Range					
Specified Value	-40~+105°C:LSAN/LLAN -40~+125°C:LSAP/LLAP				
Test Methods and Remarks	Including self-generated heat				

2. Storage Tempera	2. Storage Temperature Range		
Specified Value	-40~+85°C		
Test Methods and Remarks	0 to 40°C for the product with taping.		

# 3. Rated current

Specified Value Within the specified tolerance

4. Inductance				
Specified Value	Within the specified tolerance			
Test Methods and Remarks	Measuring equipment: LCR Meter (HP 4285A or equivalent)Measuring frequency: 2MHz, 1V			

5. DC Resistance	5. DC Resistance				
Specified Value	Within the specified tolerance				
Test Methods and Remarks	Measuring equipment : DC ohmmeter (HIOKI 3227 or equivalent)				

6. Self resonance fr	requency
Specified Value	-

7. Temperature characteristic				
Specified Value	nductance change : Within $\pm 15\%$			
Test Methods and Remarks	Measurement of inductance shall be taken at temperature range within $-40^{\circ}C \sim +85^{\circ}C$ . With reference to inductance value at $+20^{\circ}C$ ., change rate shall be calculated.			

8. Resistance to flexure of substrate					
Specified Value	No damage				
Test Methods and Remarks	The test samples shall be s until deflection of the test Test board size Test board material Solder cream thickness	-	bw. As illustrated below, apply force in the direction of the arrow indicating Force Rod $10 \xrightarrow{20}$ Board R5 $45\pm2mm$ $45\pm2mm$		



9. Insulation resistance : between wires					
Specified Value	e —				
10. Insulation resistance : between wire and core					
Specified Value	-				

 11. Withstanding voltage : between wire and core

 Specified Value

12. Adhesion of terminal electrode				
Specified Value	No abnormality.			
	The test samples shall be soldered to the test board by the reflow.			
Test Methods and Applied force : 10N to X and Y directions.				
Remarks	Duration	: 5s.		
	Solder cream thickness	: 0.12mm.		

13. Resistance to vibration					
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.				
		shall be soldered to the test board by the reflow. bmitted to below test conditions. ge 10~55Hz			
To at Mathada	Total Amplitude	1.5mm (May not exceed acceleration 196m/s <sup>2</sup> )			
Test Methods	Sweeping Method	10Hz to 55Hz to 10Hz for 1min.			
and Remarks	Time X 7	X Y For 2 hours on each X, Y, and Z axis.			
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.				

14. Solderability				
Specified Value	At least 90% of surface of terminal electrode is covered by new solder.			
T . M	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux : Ethanol solution containing rosin 25%.			
Test Methods and Remarks	Solder Temperature	245±5°C		
Remarks	Time	5±0.5 sec.		
	XImmersion depth : All sides of mounting terminal shall be immersed.			

15. Resistance to s	15. Resistance to soldering heat			
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.			
Test Methods and Remarks	The test sample shall be exposed to reflow oven at 230°C for 40 seconds, with peak temperature at $260+0/-5$ °C for 5 seconds, 3 times. Test board material : Glass epoxy-resin Test board thickness : 1.0mm Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			

16. Thermal shock							
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.						
	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.						
To at Matheada	Step	Temperature (°C)	Duration (min)				
Test Methods and Remarks	1	$-40\pm3$	$30 \pm 3$				
and Remarks	2	Room temperature	Within 3				
	3	$+85\pm2$	$30 \pm 3$				
	4	Room temperature	Within 3				
	Recovery	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.					



17. Damp heat	17. Damp heat		
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.		
Test Methods	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.		
and Remarks	Temperature	60±2°C	
	Humidity	90~95%RH	
	Time	500+24/-0 hour	
	Recovery : At least	2hrs of recovery under th	e standard condition after the test, followed by the measurement within 48hrs.

18. Loading under d	er damp heat		
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.		
Test Methods			board by the reflow. c oven set at specified temperature and humidity and applied the rated current continuously
and Remarks	Temperature	60±2°C	
anu nemarks	Humidity	90~95%RH	
	Applied current	Rated current	
	Time	500+24/-0 hour	
	Recovery : At least	2hrs of recovery under the	standard condition after the test, followed by the measurement within 48hrs.

19. Low temperatu	19. Low temperature life test		
Specified Value	Inductance change No significant abno	: Within $\pm 10\%$ prmality in appearance.	
Test Methods	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.		
and Remarks	Temperature	-40±2°C	
	Time	500+24/-0 hour	
	Recovery : At leas	t 2hrs of recovery under the	e standard condition after the test, followed by the measurement within 48hrs.

20. High temperatu	20. High temperature life test		
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.		
Test Methods	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.		
and Remarks	Temperature	85±2°C	
	Time	500+24/-0 hour	
	Recovery : At least	2hrs of recovery under the	e standard condition after the test, followed by the measurement within 48hrs.

21. Loading at high te	1. Loading at high temperature life test	
Specified Value	-	

22. Standard condition		
Specified Value	Standard test condition : Unless otherwise specified, temperature is 20±15°C and 65±20% of relative humidity. When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of 20±2°C of temperature, 65±5% relative humidity. Inductance is in accordance with our measured value.	



# PRECAUTIONS

1. Circuit Design	
Precautions	<ul> <li>Verification of operating environment, electrical rating and performance <ol> <li>A malfunction in medical equipment, spacecraft, nuclear reactors, etc. may cause serious harm to human life or have severe social ramifications. As such, any inductors to be used in such equipment may require higher safety and/or reliability considerations and should be clearly differentiated from components used in general purpose applications.</li> <li>When inductors are used in places where dew condensation develops and/or where corrosive gas such as hydrogen sulfide, sulfurous acid, or chlorine exists in the air, characteristic deterioration may occur. Please do not use inductors under such environmental conditions.</li> <li>Operating Current (Verification of Rated current) <ol> <li>The operating current including inrush current for inductors must always be lower than their rated values.</li> <li>Do not apply current in excess of the rated value because the inductance may be reduced due to the magnetic saturation effect.</li> </ol> </li> <li>Temperature rise of power choke coil depends on the installation condition in end products. Make sure that temperature rise of power choke coils in actual end products is within the specified temperature range.</li> </ol></li></ul>

2. PCB Design		
Precautions	<ul> <li>Land pattern design</li> <li>1. Please refer to a recommended land pattern.</li> </ul>	
Technical considerations	<ul> <li>Land pattern design</li> <li>Surface Mounting <ul> <li>Mounting and soldering conditions should be checked beforehand.</li> <li>Applicable soldering process to this products is reflow soldering only.</li> </ul> </li> </ul>	

3. Considerations	3. Considerations for automatic placement	
Precautions	<ul> <li>Adjustment of mounting machine</li> <li>1. Excessive impact load should not be imposed on the products when mounting onto the PC boards.</li> <li>2. Mounting and soldering conditions should be checked beforehand.</li> </ul>	
Technical	◆Adjustment of mounting machine	
considerations 1. When installing products, care should be taken not to apply distortion stress as it may deform the products.		

4. Soldering	
Precautions	<ul> <li>Reflow soldering <ol> <li>Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified.</li> <li>The product shall be used reflow soldering only.</li> <li>Please do not add any stress to a product until it returns in normal temperature after reflow soldering.</li> <li>Lead free soldering <ol> <li>When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, soldering etc sufficiently.</li> </ol> </li> </ol></li></ul>
Technical considerations	Reflow soldering <ol> <li>If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. Recommended reflow condition (Pb free solder)         300         300         100         150~180         150~180         40sec max         100         90±30sec         230°C min         Heating Time[sec]         Heating Time[sec]</li></ol>



5. Cleaning	5. Cleaning	
Precautions	Precautions         1. Washing by supersonic waves shall be avoided.	
Technical considerations	<ul> <li>Cleaning conditions</li> <li>If washed by supersonic waves, the products might be broken.</li> </ul>	

6. Handling	
Precautions	<ul> <li>Handling <ol> <li>Keep the product away from all magnets and magnetic objects.</li> </ol> </li> <li>Breakaway PC boards (splitting along perforations) <ol> <li>When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board.</li> <li>Board separation should not be done manually, but by using the appropriate devices.</li> </ol> </li> <li>Mechanical considerations <ol> <li>Please do not give the product any excessive mechanical shocks.</li> <li>Please do not add any shock and power to a product in transportation.</li> <li>Pick-up pressure <ol> <li>Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part.</li> </ol> </li> <li>Packing <ol> <li>Please avoid accumulation of a packing box as much as possible.</li> </ol> </li> </ol></li></ul>
Technical considerations	<ul> <li>Handling <ol> <li>There is a case that a characteristic varies with magnetic influence.</li> <li>Breakaway PC boards (splitting along perforations) <ol> <li>The position of the product on PCBs shall be carefully considered to minimize the stress caused from splitting of the PCBs.</li> <li>Mechanical considerations <ol> <li>There is a case to be damaged by a mechanical shock.</li> <li>There is a case to be broken by the handling in transportation.</li> <li>Pick-up pressure <ol> <li>Damage and a characteristic can vary with an excessive shock or stress.</li> </ol> </li> <li>Packing <ol> <li>If packing boxes are accumulated, that could cause a deformation on packing tapes or a damage on the products.</li> </ol> </li> </ol></li></ol></li></ol></li></ul>

7. Storage conditions	
Precautions	<ul> <li>Storage         <ol> <li>To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled.</li> <li>Storage conditions                 Ambient temperature : 0~40°C                 Humidity : Below 70% RH</li> <li>The recommended ambient temperature is below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes.                 For this reason, product should be used within 6 months from the time of delivery.                 In case of storage over 6 months, solderability shall be checked before actual usage.</li> </ol> </li> </ul>
Technical considerations	<ul> <li>Storage</li> <li>1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.</li> </ul>

